

ABSTRACT OF THE DISCLOSURE

A circuit card assembly and a method for manufacturing the circuit card assembly are disclosed. The circuit card assembly includes a printed wiring board with electronic components bonded thereto. The printed wiring board and electronic components are placed in an outer shell made of lightweight stiff material. The spaces or voids between the outer shell and the printed wiring board and the electronic components are filled with lightweight filling material and thermal filler material. The outer shell and the filling material provide increased rigidity to the electronic components and the thermal filler material increases heat transfer from a given electronic component to outside the circuit card assembly.

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